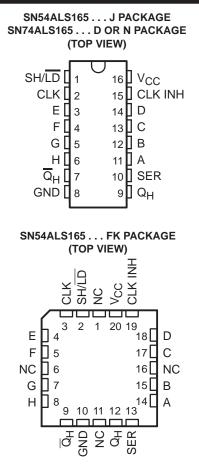
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- Complementary Outputs
- Direct Overriding Load (Data) Inputs
- Gated Clock Inputs
- Parallel-to-Serial Data Conversion
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

The 'ALS165 are parallel-load 8-bit serial shift registers that, when clocked, shift the data toward serial (Q_H and \overline{Q}_H) outputs. Parallel-in access to each stage is provided by eight individual direct data (A–H) inputs that are enabled by a low level at the shift/load (SH/LD) input. The 'ALS165 have a clock-inhibit function and complemented serial outputs.

Clocking is accomplished by a low-to-high transition of the clock (CLK) input while SH/LD is held high and the clock inhibit (CLK INH) input is held low. The functions of CLK and CLK INH are interchangeable. Since a low CLK and a low-to-high transition of CLK INH also accomplishes clocking, CLK INH should be changed to the high level only while CLK is high. Parallel loading is inhibited when SH/LD is held high. The parallel inputs to the register are enabled while SH/LD is low independently of the levels of the CLK, CLK INH, or serial (SER) inputs.



NC - No internal connection

The SN54ALS165 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ALS165 is characterized for operation from 0°C to 70°C.

	FUNCTION TABLE											
	INPUT											
SH/LD	CLK	CLK INH	FUNCTION									
L	Х	Х	Parallel load									
н	Н	Х	No change									
н	Х	Н	No change									
н	L	\uparrow	Shift [†]									
н	\uparrow	L	Shift [†]									

[†] Shift = content of each internal register shifts toward serial outputs. Data at SER is shifted into first register.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

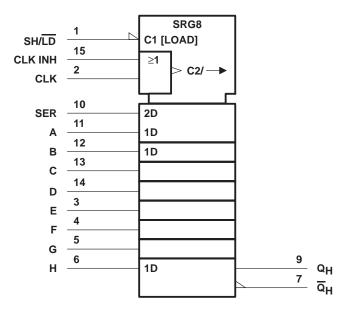


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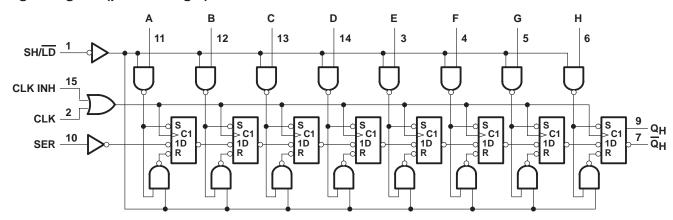
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logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

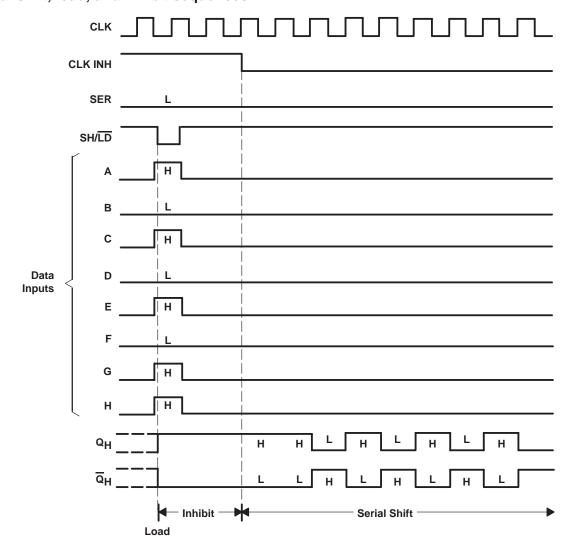


logic diagram (positive logic)

Pin numbers shown are for the D, J, and N packages.



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typical shift, load, and inhibit sequences

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Operating free-air temperature range, TA: SN54AL	S165 –55°C to 125°C
SN74AL	S165 0°C to 70°C
Storage temperature range	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



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recommended operating conditions

			SN	54ALS1	65	SN	74ALS1	65	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			0.8	V
ЮН	High-level output current				-0.4			-0.4	mA
IOL	Low-level output current				4			8	mA
fclock	Clock frequency		0		35	0		45	MHz
	Dulas duration, OLIC (and Figure 4)	CLK high	14			11			ns
^t w(CLK)	Pulse duration, CLK (see Figure 1)	CLK low	14			11			
^t w(load)	Pulse duration, SH/LD low	CLK low	15			12			ns
t _{su1}	Setup time, clock enable (see Figure 1)		15			11			ns
t _{su2}	Setup time, parallel input (see Figure 1)		11			10			ns
t _{su3}	Setup time, serial input (see Figure 2)		11			10			ns
t _{su4}	Setup time, shift (see Figure 2)		15			10			ns
t _h	Hold time at any input		4			4			ns
TA	Operating free-air temperature		-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	7507.0	TEST CONDITIONS			65	SN74ALS165			
PARAMETER	TEST C				MAX	MIN	TYP†	MAX	UNIT
VIK	$V_{CC} = 4.5 V,$	l _l = – 18 mA			-1.5			-1.5	V
V _{OH}	$V_{CC} = 4.5 V \text{ to } 5.5 V,$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2		V
	V _{CC} = 4.5 V	$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	V
V _{OL}		I _{OL} = 8 mA					0.35	0.5	V
lį	$V_{CC} = 5.5 V,$	$V_{I} = 7 V$			0.1			0.1	mA
ΙН	$V_{CC} = 5.5 V,$	V _I = 2.7 V			20			20	μΑ
Ι _{ΙL}	V _{CC} = 5.5 V,	VI = 0.4 V			-0.1			-0.1	mA
IO‡	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
ICC	V _{CC} = 5.5 V,	See Note 1		12	24		12	24	mA

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}. NOTE 1: With the outputs open, CLK INH and CLK at 4.5 V, and a clock pulse applied to SH/LD, I_{CC} is measured first with the parallel inputs at 4.5 V, then with the parallel inputs grounded.

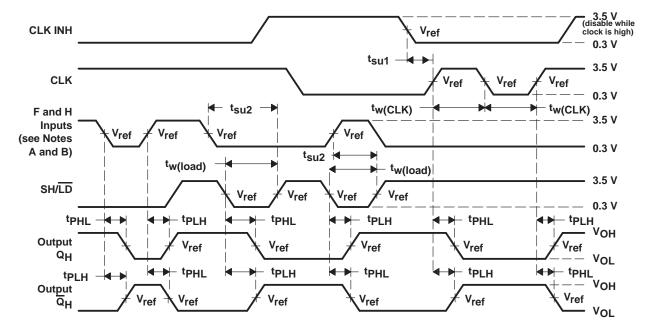


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PARAMETER	FROM (INPUT)	TO (OUTPUT)	CL RL TA	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX [†]					
				LS165					
			MIN	MAX	MIN	MAX			
fmax			35		45		MHz		
^t PLH	SH/LD	A.m.(4	23	4	20	ns		
^t PHL	SH/LD	Any	4	23	4	22			
^t PLH	01/	A	3	14	3	13			
^t PHL	CLK	Any	3	15	3	14	ns		
^t PLH			3	14	3	13			
^t PHL	Н	QH	3	18	3	16	ns		
^t PLH		<u>Q</u> H	2	17	2	15			
tрнi	Н	QH QH	3	17	3	16	ns		

IPHL 3 17

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



PARAMETER MEASUREMENT INFORMATION

NOTES: A. The remaining six data inputs and SER are low.

B. Prior to test, high-level data is loaded into the H input.

switching characteristics (see Figures 1, 2, and 3)

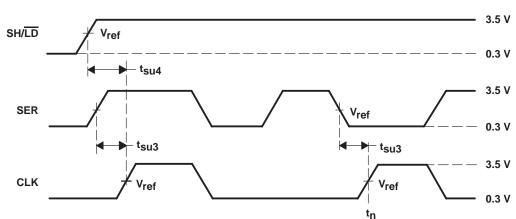
C. The input pulse generators have the following characteristics: PRR \leq 1 MHz, duty cycle \leq 50%, t_r = t_f = 2 ns.

D. V_{ref} = 1.3 V





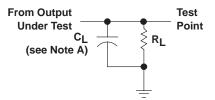
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PARAMETER MEASUREMENT INFORMATION

- NOTES: A. The eight data inputs and CLK INH are low. Results are monitored at Q_H at $t_{n + 7}$.
 - B. The input pulse generators have the following characteristics: PRR \leq 1 MHz, duty cycle = 50%, t_{f} = t_{f} = 2 ns. C. V_{ref} = 1.3 V

Figure 2. Voltage Waveforms



NOTE A: CL includes probe and jig capacitance.

Figure 3. Load Circuit for Switching Tests





PACKAGING INFORMATION

Orderable Device	Status	Package Type		Pins	-	Eco Plan	Lead finish/	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	Ball material	(3)		(4/5)	
							(6)				
SN74ALS165D	LIFEBUY	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS165	
SN74ALS165DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS165	Samples
SN74ALS165N	ACTIVE	PDIP	Ν	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS165N	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All	dimensions	are	nomina	

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS165DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1



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PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS165DR	SOIC	D	16	2500	340.5	336.1	32.0

TEXAS INSTRUMENTS

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TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
SN74ALS165D	D	SOIC	16	40	507	8	3940	4.32
SN74ALS165N	N	PDIP	16	25	506	13.97	11230	4.32
SN74ALS165N	N	PDIP	16	25	506	13.97	11230	4.32

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



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D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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